

*KBP (STD GPP) series rectifiers(KBP306G)
comparison report*

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Reversion for A

Comparison report (KBP306G)

Electrical characteristics summary:

Typical data	Subcon.-3 Typical	Result
Maximum Instantaneous Forward Voltage $V_F < 1.1V @ 3.0A$	0.920	Electrical characteristics meets with TSC specification.
Maximum Recurrent Peak Reverse Voltage $V_{RRM} > 800V @ 10.0uA$	1221	
Maximum DC Reverse Current $I_R < 10.0uA @ 800V$	0.198	
Maximum Forward Surge Current, 8.3ms sigle half sine-wave $I_{FSM} > 80A$	85	
Typical Thermal Resistance $R_{th\ j-A} = 30.0^{\circ}C/W$ (Note)	30.0	
Typical Thermal Resistance $R_{th\ j-L} = 11.0^{\circ}C/W$ (Note)	11.0	

Material information summary:

	YEW	Subcontractor-3
Die source	TSC	Yangjie
Die size (width x length) in mils	70 x 70	70 x 70
Mold compound material type	EME-1200D3 (Non-Green) & EME-EK1800G (Halogen Free)	EK-1800 (Non-Green) & EME-E120G(Halogen Free)
Bond material	Copper alloy metal	Copper alloy metal
Solder material	Pb/Sn/Ag	Pb/Sn/Ag

Note:

Unit mounted on P.C.B 10mm*10mm Copper pads, 9.5mm lead length.

Conclusion :

Subcontractor builds the product can meets with TSC's specification.

No.	Test item	Test condition	Result
1	Temperature cycling	150°C/15min, 25°C/5min -55°C/15min; 100cycles	ACC(0/22)
2	A.C	Ta:121°C P:15psig 48hrs	ACC(0/22)
3	Op-life	If=3A 168hrs	ACC(0/22)
4	Soldering heat	T:260±5°C 10sec	ACC(0/22)
5	Solderability	T:245±5°C 5sec flux: RMA type	ACC(0/22)
6	External visual	---	No change
7	X-ray	---	Result OK
8	Material	---	Result OK
9	XRF Test	---	Result OK
10	Terminal strength	---	Result OK
11	Thermal resistance	---	No difference
12	Die shear	---	Result OK

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